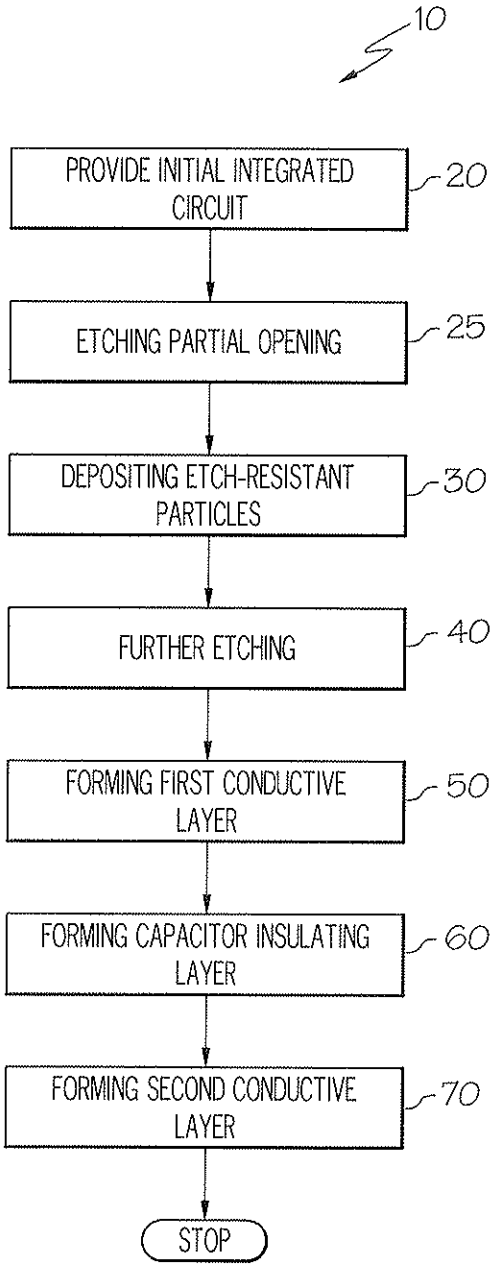

10
PROVIDE INITIAL INTEGRATED CIRCUIT
20
ETCHING PARTIAL OPENING
25
DEPOSITING ETCH-RESISTANT PARTICLES
30
FURTHER ETCHING
40
FORMING FIRST CONDUCTIVE LAYER
50
FORMING CAPACITOR INSULATING LAYER
60
FORMING SECOND CONDUCTIVE LAYER
70
STOP

FIG. 1

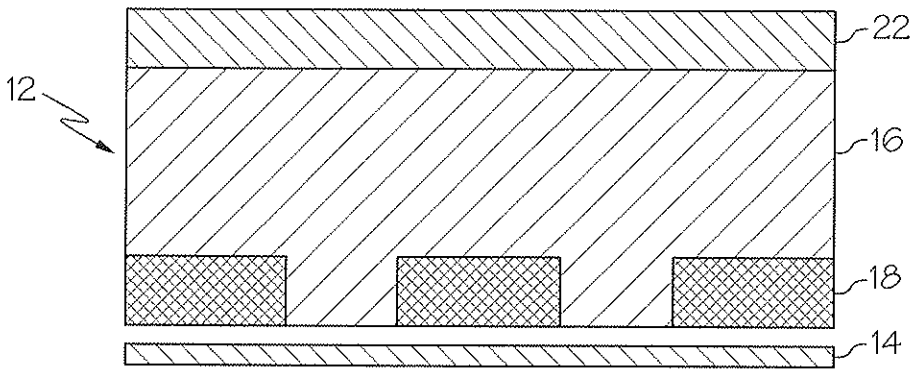


FIG. 2

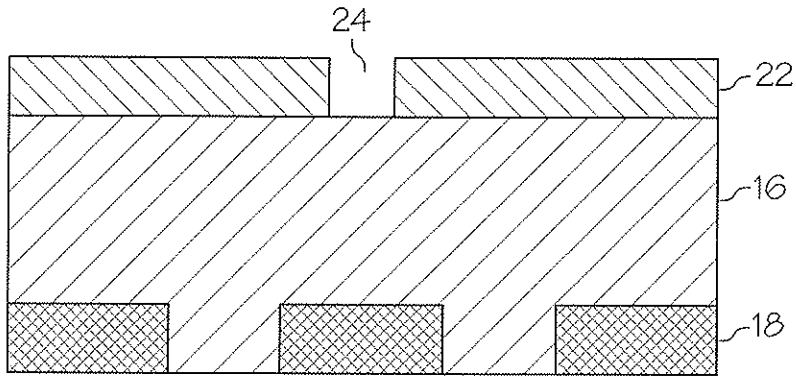


FIG. 3

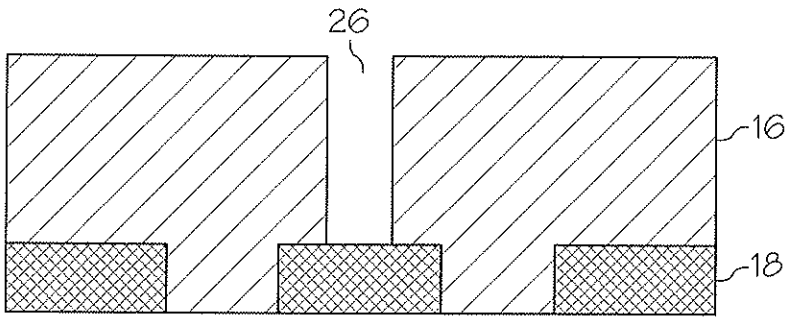


FIG. 4

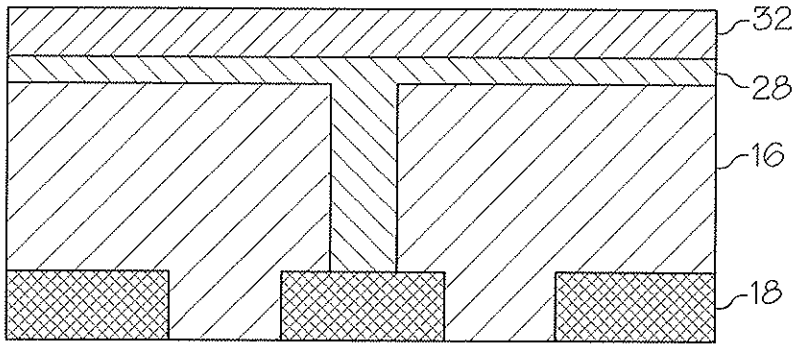


FIG. 5

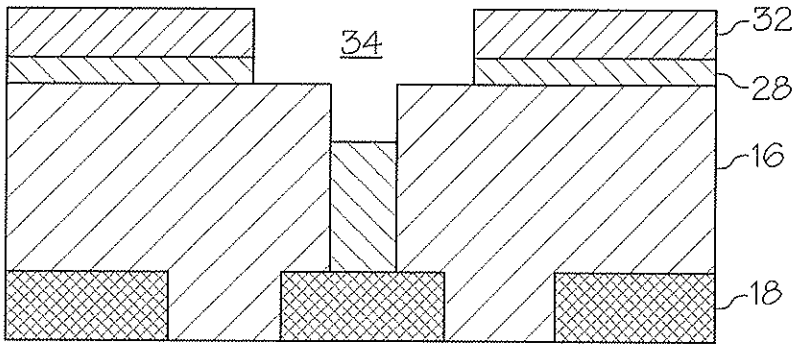


FIG. 6

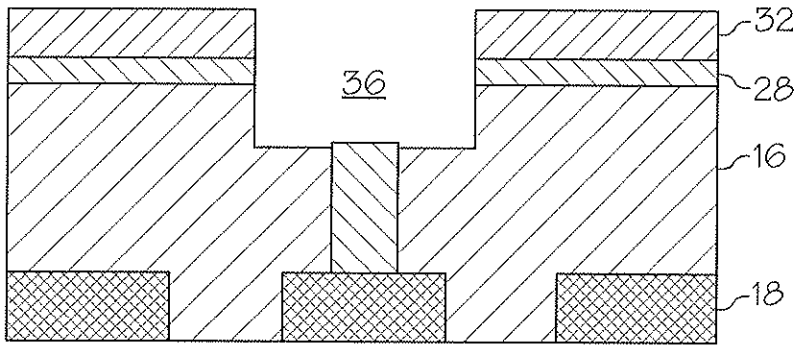


FIG. 7

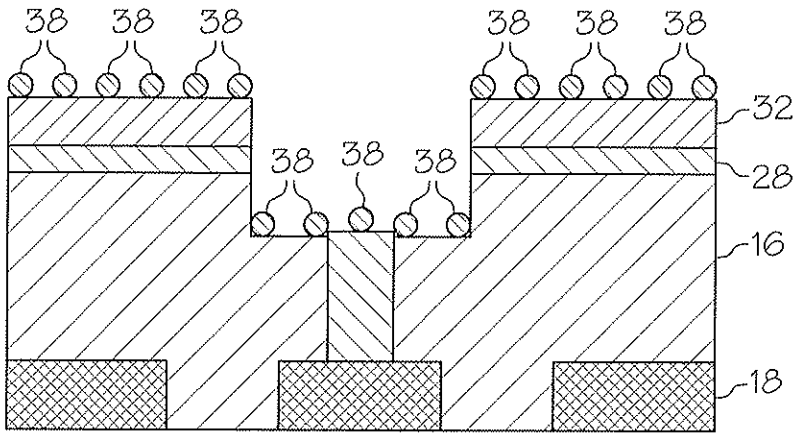


FIG. 8

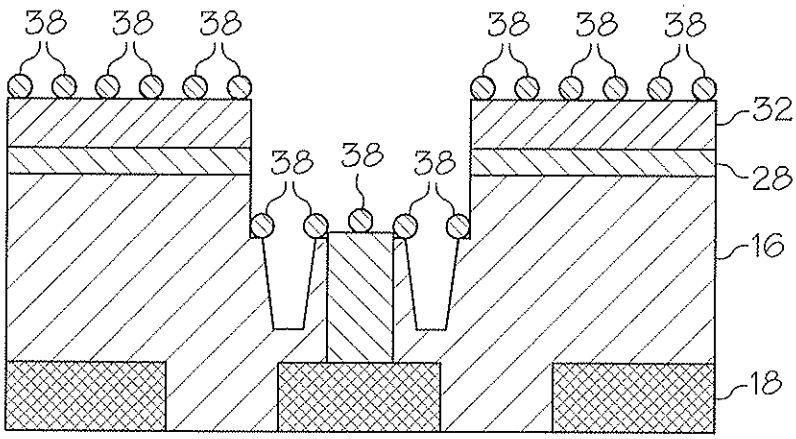


FIG. 9

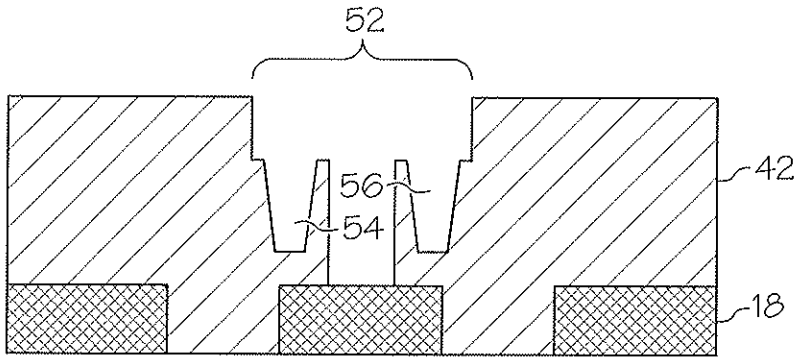


FIG. 10

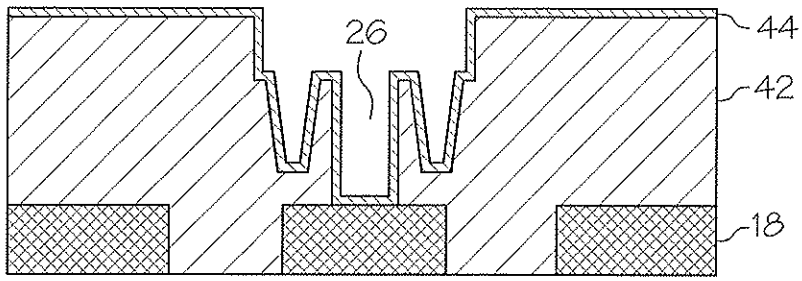


FIG. 11

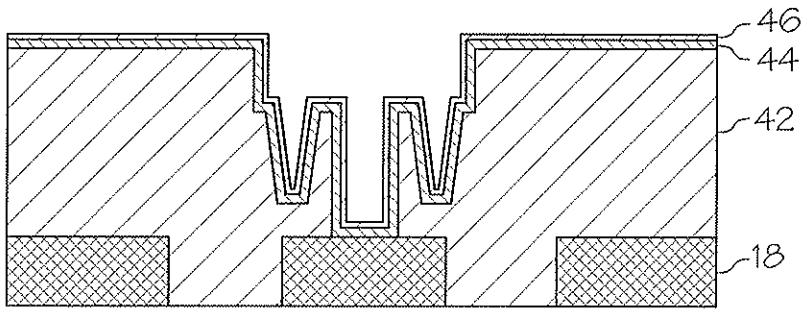


FIG. 12

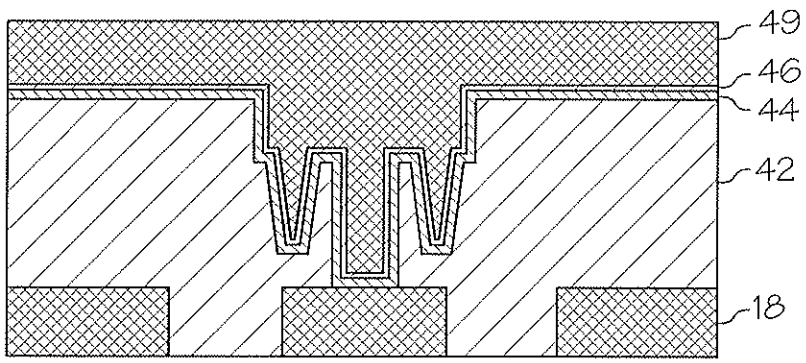


FIG. 13

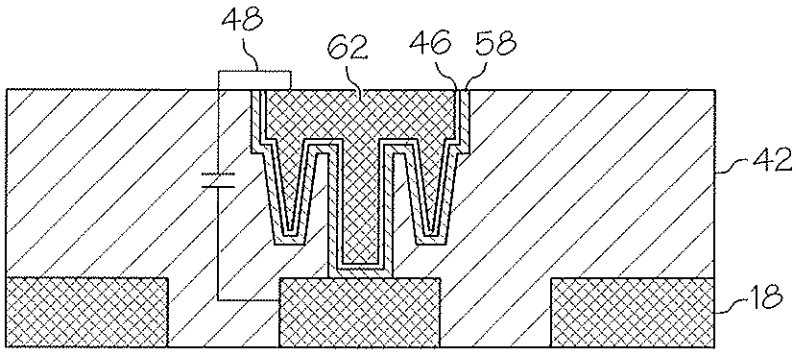


FIG. 14